Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.					under both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
1752-21.1 IPC Web Site for Information on IPC-1752 Standard http://www.ipc.org/IPC-175x				Form Type * Distribute											
Supplier	Information														
Company name*			Company unique ID				Unique ID Authority				Response Date*				
onsemi												2024-05-17			
Contact Name			Title - Contact				Phone - Contact*				Email - Contact*				
Product-E	Product-Env-Stewards			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Authorized	Authorized Representative*			Title - Representative			Phone - Representative*			Email	Email - Representative*				
Product-E	Product-Env-Stewards			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
	Requester Item Number Mfr Item		Number Mfr Item Name				Effective Date	Version	Manufacturing Site	Manufacturing Site		UOM	Unit Type		
NV25320		0DTHFT3G	T3G 32KB SPI SER CMOS EEPROM TSS		TSSOP8	2024-05-17		PH1		31.2	mg	Each			
Manufacturing Process Information															
	Terminal Plating / Grid Array Material			Alloy	J-STD-020 MSL	Rating	Peak Proces	s Body Tempe	rature Max Time at Pe	ak Temper	ature Number	of Reflow Cycles			
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)			CU Alloy 1		1		260 C		30	seco	ids 3				
Comments	Comments														
level 1 - maximum time at peak temperature during soldering is 10-30 seconds															
For more i	information regarding material co	mposition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.66	mg	Supplier	Silicon (Si)	7440-21-3		0.66	mg
Die Attach	0.12	mg		Epoxy resin	proprietary data		0.012	mg
			Supplier	Silver (Ag)	7440-22-4		0.096	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.012	mg
Lead Frame	10.96	mg	Supplier	Zinc (Zn)	7440-66-6		0.0132	mg
			Supplier	Iron (Fe)	7439-89-6		0.2576	mg
			Supplier	Copper (Cu)	7440-50-8		10.686	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0033	mg
Mold Compound-Black	19.21	mg		Epoxy resin	proprietary data		1.4408	mg
			Supplier	Phenolic Resin	Proprietary Data		0.4802	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		1.4408	mg
			Supplier	Carbon Black (C)	1333-86-4		0.096	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		15.7522	mg
Plating	0.12	mg	Supplier	Palladium (Pd)	7440-05-3		0.006	mg
			В	Nickel (Ni)	7440-02-0		0.108	mg
			Supplier	Gold (Au)	7440-57-5		0.006	mg
Wire Bond - Au	0.13	mg	Supplier	Gold (Au)	7440-57-5		0.13	mg